

In re application of: Hoe-Seong HA and Jun-Eui SONG

Serial No.

09/765,543

Examiner:

Estrada, Michelle

Filed:

January 19, 2001

Group Art Unit: 2823

For:

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BORDERLESS CONTACT STRUCTURE AND METHOD OF FORMING

THE SAME

Confirmation No. 1427

BOX NON FEE AMENDMENT Assistant Commissioner for Patents, Washington, D.C. 20231

Responsive to the Office Action dated December 3, 2002 enclosed is an response to office action in the above-identified application.

The fee has been calculated as shown below.

CLAIMS AS AMENDED					
For:	Number After Amendment	Previous Number	Extra	Rate	Additional Fee
Total Claims	10	10	0	x \$18 =	\$0.00
Independent Claims	1	1	0	- x \$84 =	\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

^{*}greater of twenty (20) or number for which fee has been paid

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Any deficiency or overpayment should be charged or credited to deposit account number 1703.

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

20575

PATENT TRADEMARK OFFICE

Reg. No. 28,881

MARGER JOHNSON & McCOLLOM, P.C. 1030 SW Morrison Street Portland, OR 97205 (503) 222-3613

I HEREBY CERTIFY THAT THIS COR-RESPONDENCE IS BEING DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS FIRST CLASS MAIL IN AN ENVELOPE ADDRESSED TO:

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^{**}greater of three (3) or number for which fee has been paid



PATENT APPLICATION

Doc. No. 4591-160

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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BOX NON FEE AMENDMENT Assistant Commissioner for Patents Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Responsive to the Office Action, dated December 3, 2002 please amend the ation as follows.

IN THE CLAIMS

1. A borderless contact structure comprising:

a semiconductor substitute. application as follows.

a semiconductor substrate having a top surface;

a device isolation region formed in a predetermined region of the semiconductor substrate, the device isolation region having a protrusion that is higher in level than the top surface of the semiconductor substrate;

an impurity diffusion region formed in an active region surrounded by the device isolation region;

an etch stop spacer formed overlying a sidewall of the protrusion;

an etch stop layer and an interlayer insulating layer sequentially formed over the resultant structure; and

a contact hole opening the interlayer insulating layer and the etch stop layer, the contact hole exposing at least a portion of the impurity diffusion region.